

Product Description

Shin-Etsu's X-23-8032 is a curable grease that acts as a thermal interface gap filler and provides excellent thermal conductivity and low thermal resistance. X-23-8032 has high natural tackiness to anchor itself to necessary substrates, but develops no chemical adhesion to allow for superior reworkability.

Product Features

- Excellent thermal conductivity
- Superior reworkability
- Low thermal resistance

Typical Applications

- Electronics applications requiring thermal dissipation

Typical Properties

Type	Liquid-dispensed Gap Filling Rubber
Cure Type	Addition
One/Two Component	One
Low Molecular Weight Siloxane Stripped?	Y
Color	White
Density @ 23C (g/cm ³)	3.37
Viscosity (Pa·s)	236
Cure Conditions	1hr @ 120C
Lap Shear Strength (MPa)	0.1
Thermal Conductivity (W/m·K)	3.00
Thermal Resistance (mm ² ·K/W)	8
% Volatile Content	0.11
Usable Temp. Range (C)	-40 to +180
Bond Line Thickness (µm)	13

Note: Values are not for specification purposes.

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